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April 1st, 2010 Renesas Electronics Corporation

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BIPOLAR ANALOG INTEGRATED CIRCUIT μ PC3533,3504

THREE-THERMAL POSITIVE OUTPUT VOLTAGE

DESCRIPTION

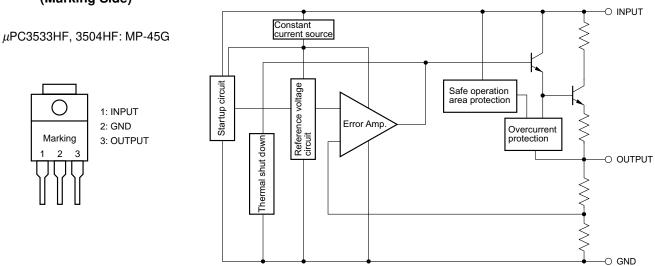
The μ PC3533 and 3504 are three-thermal positive output voltage regulators with an output current of 1 A at respective output voltages of 3.3 and 4 V. These regulators are guaranteed to operate at as low as -40° C.

FEATURES

- Output current capacity: 1 A
- On-chip overcurrent limiter
- On-chip output transistor safe operation area protection
- On-chip thermal protection
- Output capacitor capacitance: 0.1 µF or higher
- Wide operating temperature range: $T_A = -40$ to $+85^{\circ}C$

PIN CONFIGURATION (Marking Side)

BLOCK DIAGRAM



ORDERING INFORMATION

Part Number	Package	Outputs	Marking	Packing Type
μ PC3533HF	MP-45G (Isolated TO-220)	3.3 V	3533	 Bag stuffing
μ PC3540HF	MP-45G (Isolated TO-220)	4.0 V	3504	 Bag stuffing

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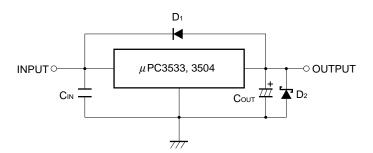
ABSOLUTE MAXIMUM RATINGS (TA = 25°C unless otherwise specified)

Parameter	Symbol	Rating	Unit
Input Voltage	VIN	-0.3 to +25	V
Internal Power Dissipation ($T_c = 25^{\circ}C$)	P⊤	15 Note	W
Operating Ambient Temperature	Та	-40 to +85	°C
Operating Junction Temperature	TJ	-40 to +150	°C
Storage Temperature	Tstg	-55 to +150	°C
Thermal Resistance (junction to case)	Rth(J-C)	7	°C/W
Thermal Resistance (junction to ambient)	Rth(J-A)	65	°C/W

Note Internally limited. When the operating junction temperature rises over 150°C, the internal circuit shuts down the output voltage.

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

TYPICAL CONNECTION



- CIN: 0.1 to 0.47 μ F or higher. Set this value according to the length of the line between the regulator and INPUT pin. Be sure to connect CIN to prevent parasitic oscillation. Use of a film capacitor or other capacitor with excellent voltage and temperature characteristics is recommended. If using a laminated ceramic capacitor, it is necessary to ensure that CIN is 0.1 μ F or higher for the voltage and temperature range to be used.
- Cout: 0.1 μ F or higher. Be sure to connect Cout to prevent oscillation and improve excessive load regulation. Place CIN and Cout as close as possible to the IC pins (within 2 cm). Also, use an electrolytic capacitor with low impedance characteristics if considering use at sub-zero temperatures.
- D1: If the OUTPUT pin has a higher voltage than the INPUT pin, connect a diode.
- D2: If the OUTPUT pin has a lower voltage than the GND pin, connect a Schottky barrier diode.

Caution Make sure that no voltage is applied to the OUTPUT pin from external.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Type Number	MIN.	TYP.	MAX.	Unit
Input Voltage	VIN	μPC3533	5.8		20	V
		μPC3504	6.5		20	V
Output Current	lo	All	0.005		1	А

Caution Use of conditions other than the above-listed recommended operating conditions is not a problem as long as the absolute maximum ratings are not exceeded. However, since the use of such conditions diminishes the margin of safety, careful evaluation is required before such conditions are used. Moreover, using the MAX. value for all the recommended operating conditions is not guaranteed to be safe.

ELECTRICAL CHARACTERISTICS

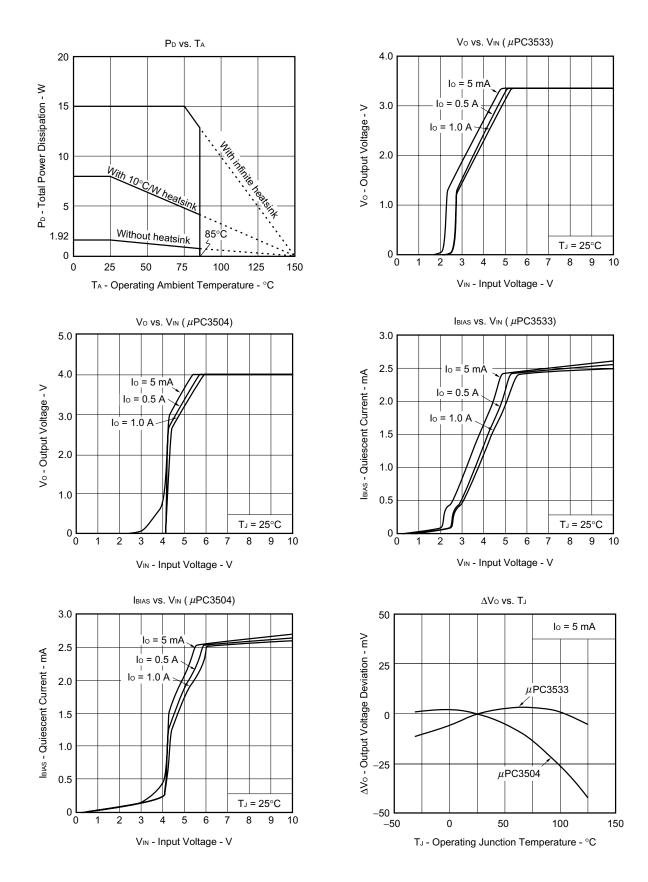
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Output Voltage	V ₀₁		3.168	3.3	3.432	V
	V _{O2}	5.8 V \leq V in \leq 20 V, 5 mA \leq lo \leq 1 A	3.135		3.465	V
Line Regulation	REGIN1	$5.8 \text{ V} \leq V_{IN} \leq 20 \text{ V}$		20	50	mV
	REG _{IN2}	$5.8~V \le V_{\text{IN}} \le 9~V$		10	30	mV
Load Regulation	REG∟1	$5 \text{ mA} \le \text{lo} \le 1 \text{ A}$		20	50	mV
	REGL2	$250 \text{ mA} \le \text{lo} \le 750 \text{ mA}$		10	20	mV
Quiescent Current	Ibias			2.8	6	mA
Quiescent Current Change		$5.8~V \leq V_{IN} \leq 20~V$			1.0	mA
Output Noise Voltage	Vn	10 Hz \leq f \leq 100 kHz		55		μ Vr.m.s.
Ripple Rejection	R•R	$f=120~Hz,~5.8~V\leq V_{\text{IN}}\leq 9~V$		57		dB
Dropout Voltage	VDIF	lo = 1 A		2.0	2.5	V
Short Circuit Current	IOshort1	Vin = 5.8 V		1.8		А
Peak Output Current	lOpeak	Vin = 10 V	1.0	2.1	2.8	А
Temperature Coefficient of	ΔVo/ ΔT	$I_0 = 5 \text{ mA}, 0^\circ C \le T_J \le 125^\circ C$		-0.4		mV/°C
Output Voltage						

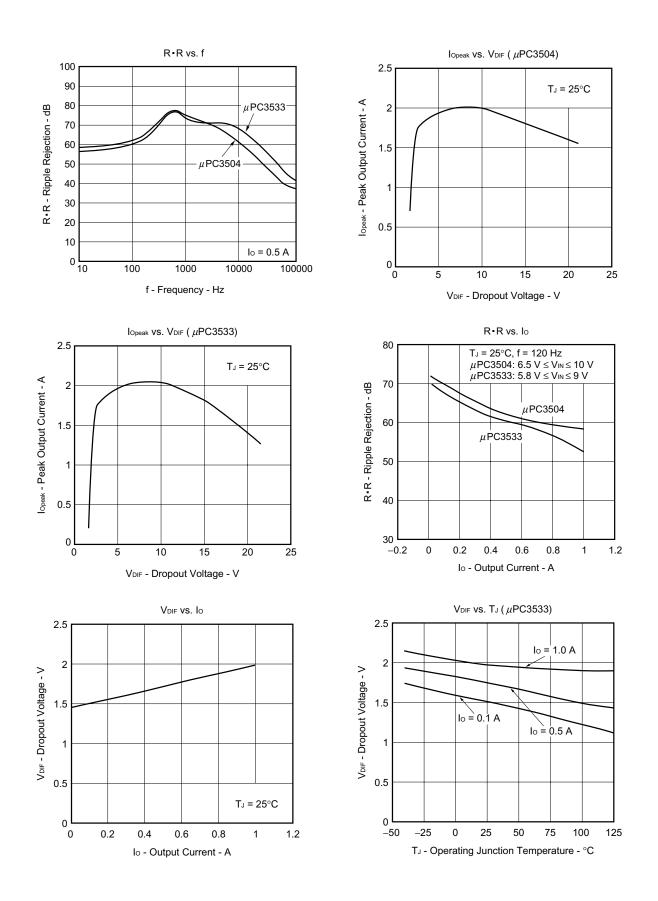
μ PC3533 (T_J = 25°C, V_{IN} = 5.8 V, Io = 0.5 A, C_{IN} = 0.33 μ F, Cout = 0.1 μ F, unless otherwise specified)

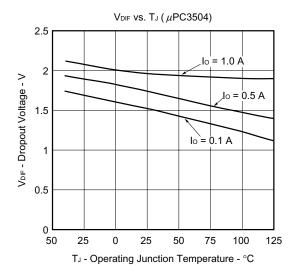
μ PC3504 (T_J = 25°C, V_{IN} = 6.5 V, Io = 0.5 A, C_{IN} = 0.33 μ F, Cout = 0.1 μ F, unless otherwise specified)

	,				,	
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Output Voltage	V ₀₁		3.84	4.0	4.16	V
	V _{O2}	6.5 V \leq VIN \leq 20 V, 5 mA \leq lo \leq 1 A	3.80		4.20	V
Line Regulation	REGIN1	$6.5~V \leq V_{\text{IN}} \leq 20~V$		20	50	mV
	REG _{IN2}	$6.5~V \le V_{\text{IN}} \le 10~V$		10	30	mV
Load Regulation	REG _{L1}	$5 \text{ mA} \le \text{lo} \le 1 \text{ A}$		20	50	mV
	REGL2	250 mA \leq lo \leq 750 mA		10	20	mV
Quiescent Current	IBIAS			2.8	6	mA
Quiescent Current Change		$6.5~V \leq V_{\text{IN}} \leq 20~V$			1.0	mA
Output Noise Voltage	Vn	10 Hz \leq f \leq 100 kHz		55		μ Vr.m.s.
Ripple Rejection	R•R	f = 120 Hz, 6.5 V \le V IN \le 10 V		60		dB
Dropout Voltage	VDIF	lo = 1 A		2.0	2.5	v
Short Circuit Current	IOshort1	Vin = 6.5 V		1.8		А
Peak Output Current	lOpeak	V _{IN} = 10 V	1.1	2.1	2.8	А
Temperature Coefficient of	ΔVo/ ΔT	$I_0 = 5 \text{ mA}, 0^\circ C \le T_J \le 125^\circ C$		-0.4		mV/°C
Output Voltage						

* TYPICAL CHARACTERISTICS (Reference Values)



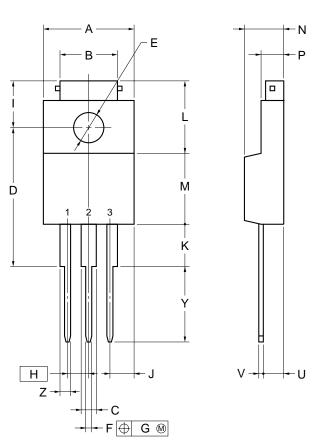




PACKAGE DRAWING

μ PC3533HF, 3504HF

3PIN PLASTIC SIP (MP-45G)



NOTE

Each lead centerline is located within 0.25 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
Α	10.0±0.2
В	7.0±0.2
С	1.50±0.2
D	17.0±0.3
E	\$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$
F	0.75±0.10
G	0.25
Н	2.54 (T.P.)
I	5.0±0.3
J	2.46±0.2
К	5.0±0.2
L	8.5±0.2
М	8.5±0.2
Ν	4.5±0.2
Р	2.8±0.2
U	2.4±0.5
V	0.65±0.10
Y	8.9±0.7
Z	1.30±0.2
	P3HF-254B-4

RECOMMENDED MOUNTING CONDITIONS

The following conditions must be met for mounting conditions of the μ PC3533, 3504.

For more details, refer to the Semiconductor Device Mounting Technology Manual (C10535E).

Please consult with our sales offices in case other mounting process is used, or in case the mounting is done under different conditions.

Type of Through-hole Device

μPC3533HF, 3504HF: MP-45G

Process	Conditions
Wave Soldering (only to leads)	Solder temperature: 260°C or below, Flow time: 10 seconds or less
Partial Heating Method	Pin temperature: 300°C or below, Heat time: 3 seconds or less (Per each pin).

Caution For through-hole device, the wave soldering process must be applied only to leads, and make sure that the package body does not get jet soldered.

REFERENCE DOCUMENTS

Document Name		Document No.
Usage of Three-Terminal Regulators	User's Manual	G12702E
Review of Quality and Reliability Handbook	Information	C12769E
NEC Semiconductor Device Reliability/Quality Control System	Information	C10983E
Semiconductor Device Mounting Technology Manual	Information	C10535E
SEMICONDUCTOR SELECTION GUIDE - Products and Packages-	X13769X	

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